PRODUCT / PROCESS CHANGE NOTIFICATION

| 1. PCN basic data | | | |
|----------------------|--|--|--|
| 1.1 Company | | TMicroelectronics International N.V | |
| 1.2 PCN No. | | AMG/18/10669 | |
| 1.3 Title of PCN | | Qualification of ASE WeiHai for D2PAK package (GPA Division) | |
| 1.4 Product Category | | See attached product list | |
| 1.5 Issue date | | 2018-02-14 | |

| 2. PCN Team | |
|---------------------------|--------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | ROBERTSON HEATHER |
| 2.1.2 Phone | +1 8475853058 |
| 2.1.3 Email | heather.robertson@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Lorenzo NASO |
| 2.1.2 Marketing Manager | Marcello SAN BIAGIO |
| 2.1.3 Quality Manager | Jean-Marc BUGNARD |

| 3. Change | | |
|--------------|---|-------------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| | Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617) | - ST Shenzhen - ASE WeiHai |

| 4. Description of change | | |
|---|---|---|
| | Old | New |
| 4.1 Description | Assembly, Test and Finishing : - ST Shenzhen | Assembly, Test and Finishing : - ST Shenzhen - ASE WeiHai |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No impact | |

| 5. Reason / motivation for change | |
|-----------------------------------|--|
| | The introduction of ASE WeiHai for both Assembly and Test & Finishing activities will allow us to rationalize our manufacturing assets and improve our manufacturing process for higher volume production in order to provide a better support to our customers. |
| 5.2 Customer Benefit | CAPACITY INCREASE |

| 6. Marking of parts / traceability of change | |
|--|------------------------|
| 6.1 Description | New finished good code |

| 7. Timing / schedule | |
|-------------------------------------|--------------|
| 7.1 Date of qualification results | 2018-01-12 |
| 7.2 Intended start of delivery | 2018-05-19 |
| 7.3 Qualification sample available? | Upon Request |

| 8. Qualification / Validation | | | |
|---|---|---------------|------------|
| 8.1 Description | 10669 399-W-17-Qualification Subcon D2pak package Cu wire in As | se Weihai.p | df |
| 8.2 Qualification report and qualification results | | Issue Date | 2018-02-14 |

9. Attachments (additional documentations)

10669 Public product.pdf 10669 399-W-17-Qualification Subcon D2pak package Cu wire in Ase Weihai.pdf

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| | 10. 1 Current | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| 497-1170-2-ND | L7805ABD2T-TR | |
| L7805ABD2T-TR | L7805ABD2T-TR | |
| 497-1171-2-ND | L7805CD2T-TR | |
| L7805CD2T-TR | L7805CD2T-TR | |
| 497-1571-2-ND | LM317D2T-TR | |
| LM317D2T-TR | LM317D2T-TR | |



Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : Qualification of ASE WeiHai for D2PAK package (GPA Division) *PCN Reference :* AMG/18/10669

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

| L7805CD2T-TR L7805ABD2T | LM317D2T-TR |
|-------------------------|-------------|
|-------------------------|-------------|

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